

CURRENT LEAD FREE DRAM OFFERED BY ISSI

Q: How do we differentiate Lead Free Product from Non-Lead Free Product?

A: The package code for Lead Free is different from a Non Lead Free Product. For example, a Non-Lead Free 54-pin TSOP-II has a package designator of 'T' and the Lead Free 54-pin TSOP-II has a package designator of 'TL'. We simply added a 'L' to the old package code.

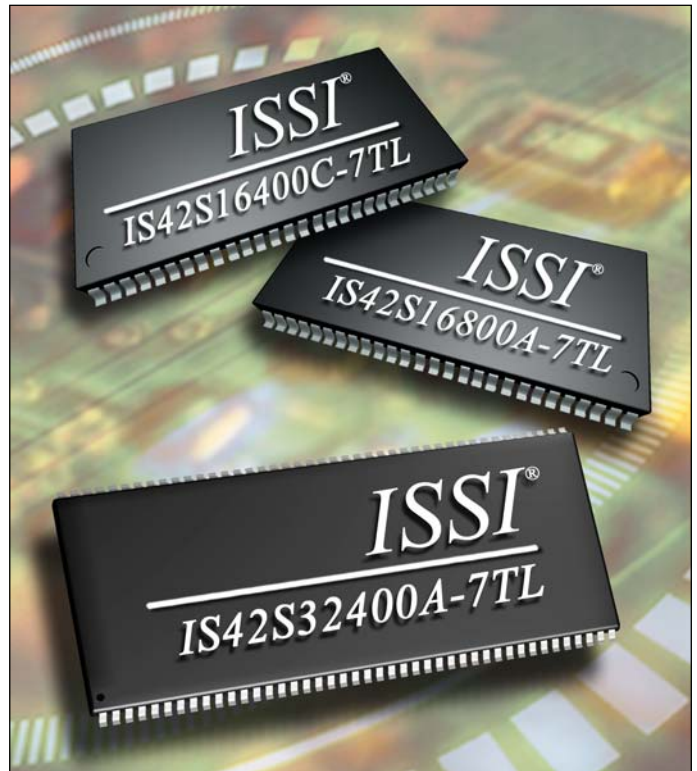
Q: Is it RoHS Compliant?

RoHS - European Union's Restriction on Hazardous Substances Directive (which bans the industry's use of lead, mercury, cadmium, hexavalent chromium and two brominated flame retardants –PBB and PBDE).

A: Yes

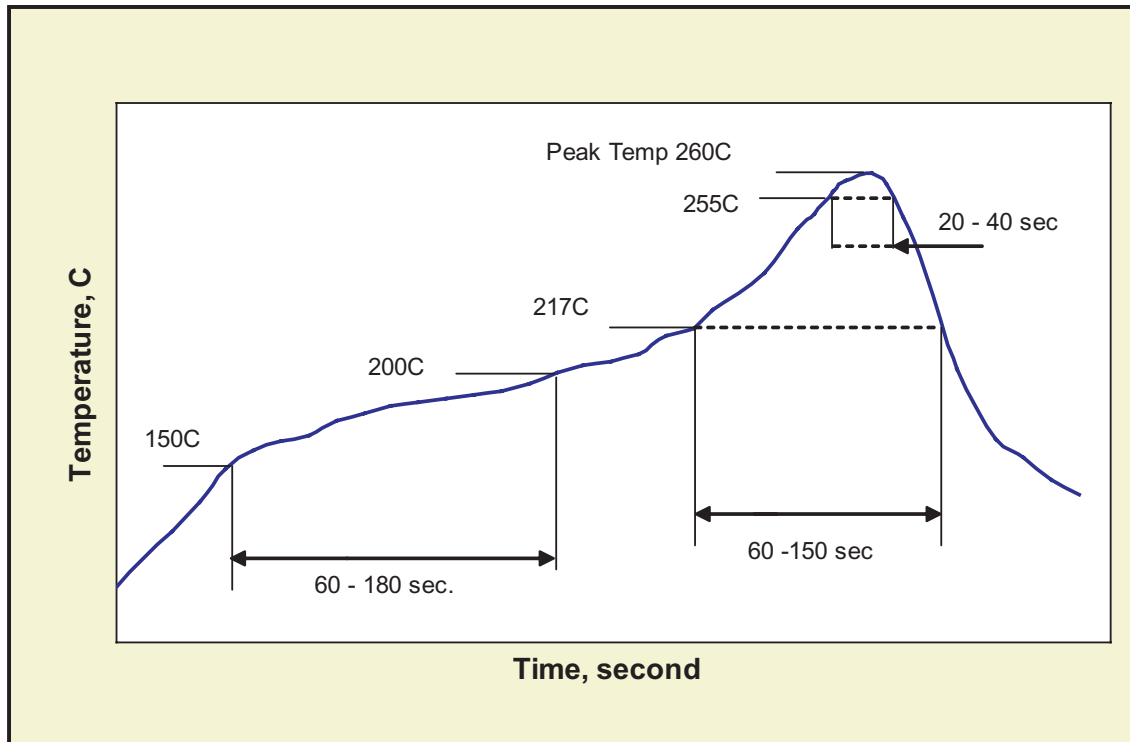
Q: What is the plating for lead frame finger?

A: 100% Matte Tin



Part Number	Configuration	Speed	Package
IS42S16100C/C1	1M x16 Synchronous DRAM, 3.3V	6, 7	T
IS42S16400B/C	4M x16 Synchronous DRAM, 3.3V	6, 7	T
IS42S16800A	8M x16 Synchronous DRAM, 3.3V	6, 7	T
IS42S16800AL	Power Saver 8M x16 SynchronousDRAM, 3.3V	7, 10	T
IS42S32200B/C	2M x 32 Synchronous DRAM, 3.3V	6, 7	T
IS42S32400A	4M x 32 Synchronous DRAM, 3.3V	7	T
IS42S32400AL	Power Saver 4M x 32 Synchronous DRAM, 3.3V	7, 10	T
IS42S81600A	16M x 8 Synchronous DRAM, 3.3V	7	T
IS42S81600AL	Power Saver 16M x 8 Synchronous DRAM, 3.3V	7, 10	T
IS42S16160A	16M x 6 Synchronous DRAM, 3.3V	6, 7	T
IS42S46400A	64M x 4 Synchronous DRAM, 3.3V	6, 7	T
IS42S83200A	16M x 6 Synchronous DRAM, 3.3V	6, 7	T

IR Reflow Temperature Profile (Pb-Free)



ISSI Spec

Average ramp-up rate	< 3°C/sec
Preheat temperature 150°C to 200°C	60 – 180 sec
Temperature maintained above 217°C	60 – 150 sec
Peak temperature	260°C
Temperature > 255°C	20 – 40 sec
Ramp-down rate	< 6°C/sec